

## -140A -60V P-channel Enhancement Mode Power MOSFET

### 1 Description

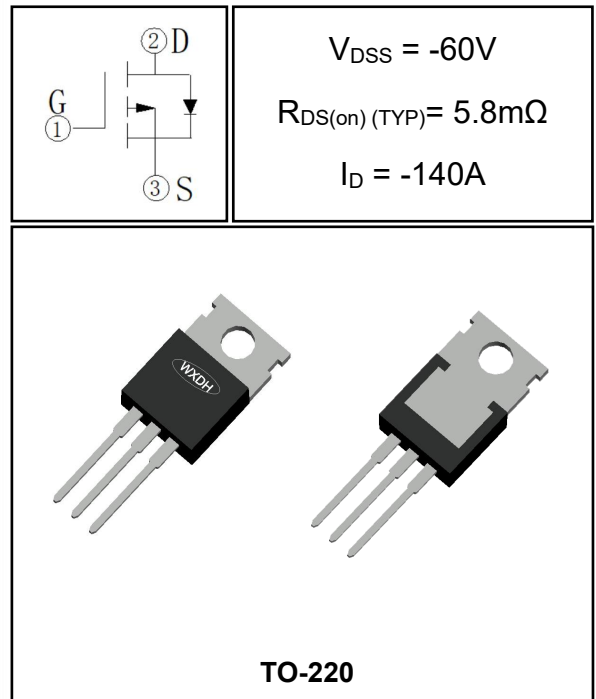
These P-channel enhancement mode power mosfets used advanced trench technology design, provided excellent  $R_{DS(on)}$  and low gate charge. Which accords with the RoHS standard.

### 2 Features

- Low on resistance
- Low gate charge
- Low reverse transfer capacitances
- Fast switching
- 100% single pulse avalanche energy test

### 3 Applications

- Power switching applications
- Inverter management system
- Power tools



### 4 Electrical Characteristics

#### 4.1 Absolute Maximum Ratings (T<sub>c</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-to-Source Voltage	V <sub>DSS</sub>	-60	V
Gate-to-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	T <sub>C</sub> =25°C	-140
		T <sub>C</sub> =100°C	-99
Pulsed Drain Current <sup>(1)</sup>	I <sub>DM</sub>	-560	A
Single Pulse Avalanche Energy <sup>(4)</sup>	E <sub>AS</sub>	1369	mJ
Power Dissipation	P <sub>tot</sub>	T <sub>a</sub> =25°C	2.5
		T <sub>C</sub> =25°C	208
Junction Temperature Range	T <sub>j</sub>	-55~150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~150	°C

#### 4.2 Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Units
Thermal Resistance, Junction to Case-sink	R <sub>thJC</sub>	--	0.45	0.6	°C/W
Thermal Resistance, Junction to Ambient	R <sub>thJA</sub>	--	50	65	°C/W

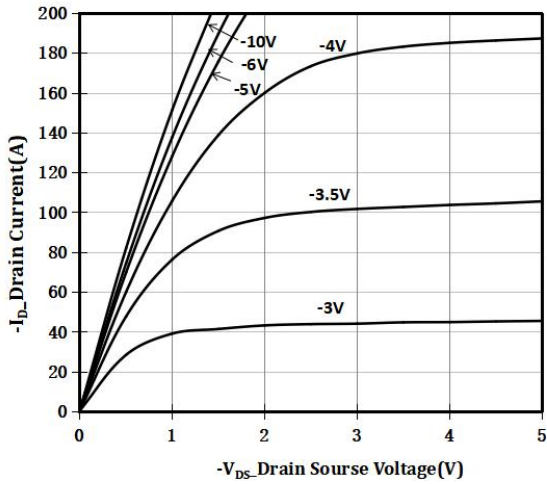
**4.3 Electrical Characteristics** (Tc=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
<b>Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$I_D=-250\mu A, V_{GS}=0V$	-60	--	--	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=-60V, V_{GS}=0V, T_C=25^\circ C$	--	--	-1	$\mu A$
		$V_{DS}=-60V, V_{GS}=0V, T_C=125^\circ C$	--	--	-100	$\mu A$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	--	-2	V
Drain-to-Source on-state Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-60A$	--	5.8	6.6	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=-30V, f=1.0MHz$	--	12668	--	pF
Output Capacitance	$C_{oss}$		--	736	--	
Reverse Transfer Capacitance	$C_{rss}$		--	509	--	
Gate Resisitance	$R_G$	$V_{DD}=0V, V_{GS}=0V, F=1MHz$	--	3.8	--	$\Omega$
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{gs}=-10V, V_{ds}=-30V, I_d=-60A, R_g=3\Omega$	--	15.5	--	nS
Turn-on Rise Time	$t_r$		--	44	--	
Turn-off Delay Time	$t_{d(off)}$		--	228	--	
Turn-off Fall Time	$t_f$		--	85	--	
Total Gate Charge	$Q_g$	$V_{gs}=-10V, V_{ds}=-30V, I_d=-60A$	--	247	--	nC
Gate-to-Source Charge	$Q_{gs}$		--	56	--	
Gate-to-Drain("Miller")	$Q_{gd}$		--	41	--	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=-60A$	--	--	-1.2	V
Diode Forward Current	$I_S$		--	--	-140	A
Reverse Recovery Time <sup>(3)</sup>	$t_{rr}$	$T_J=25^\circ C, I_F=-60A, di_F/dt=-100A/us, V_{GS}=0V$	--	41	--	nS
Reverse Recovery	$Q_{rr}$		--	51	--	nC

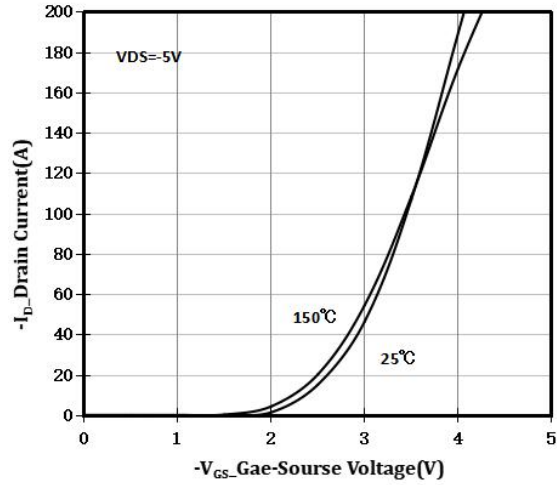
**Notes:**

- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board,  $t_s \leq 10sec$ .
- 3: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4:  $L=0.5mH, V_{DD}=-20V, V_{GATE}=-60V, Start T_J=25^\circ C$ .

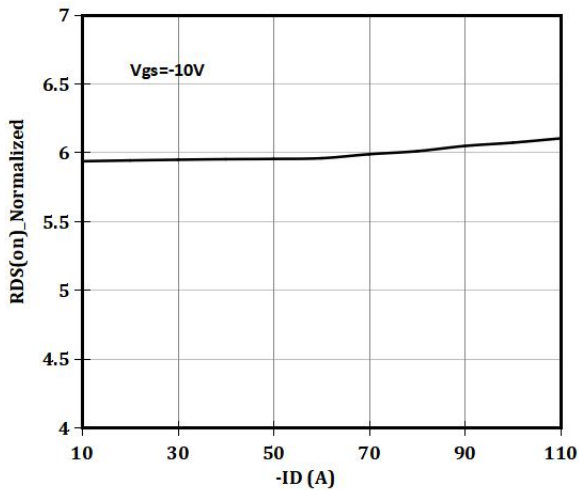
**5. Typical characteristics diagrams**



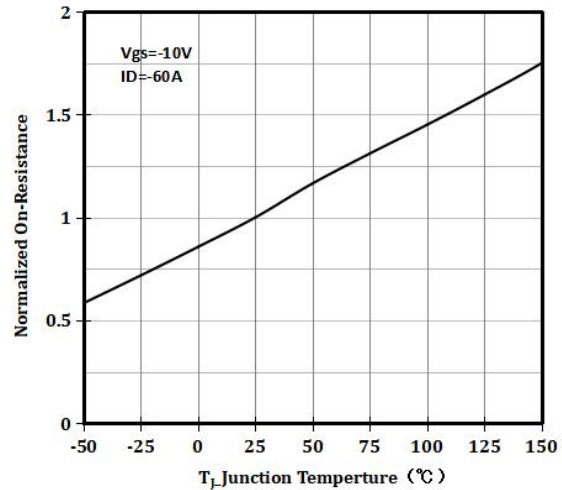
**Figure 1 Output Characteristics**



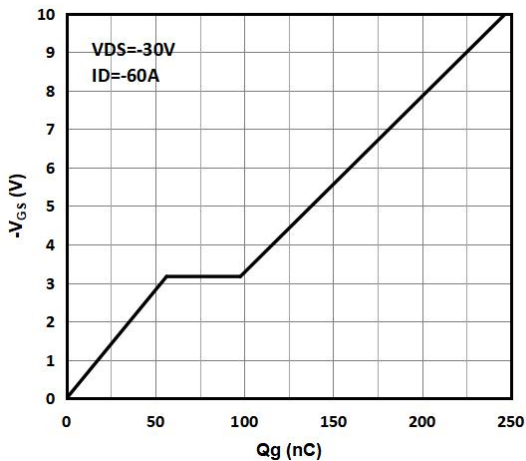
**Figure 2 Transfer Characteristics**



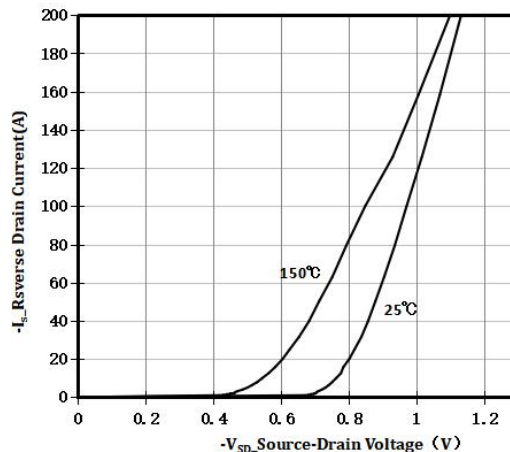
**Figure 3 Rdson- Drain Current**



**Figure 4 Rdson-Junction Temperature**

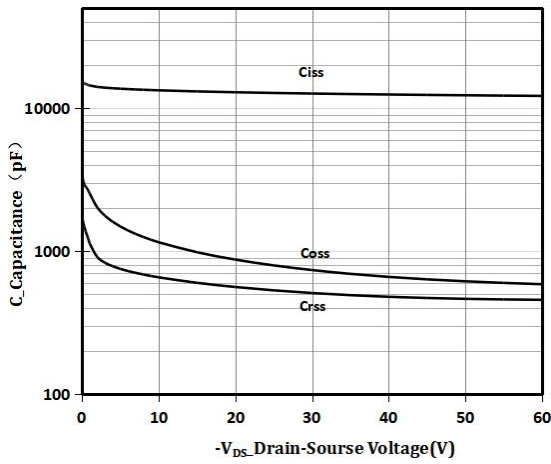


**Figure 5 Gate Charge**

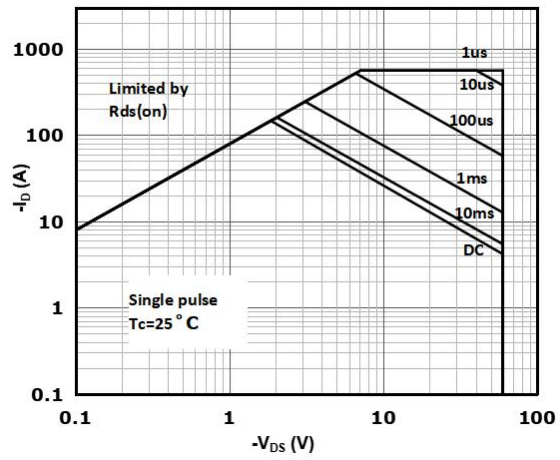


**Figure 6 Source- Drain Diode Forward**

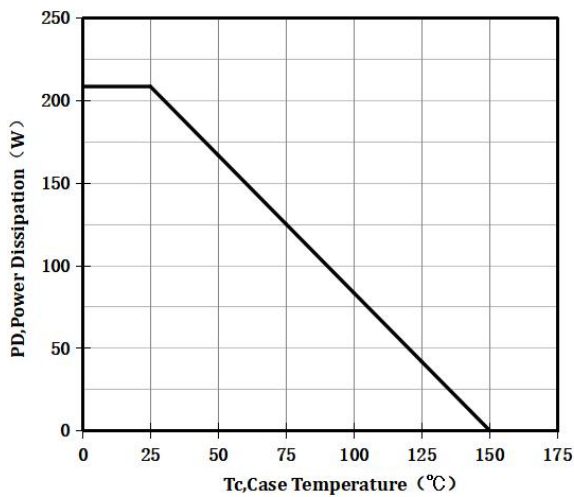
**5 Typical characteristics diagrams(continues)**



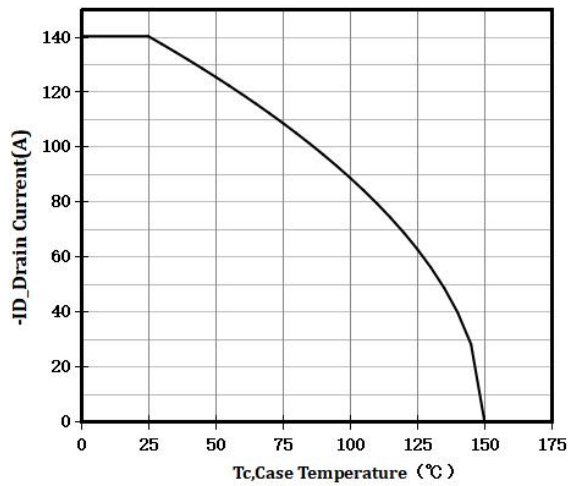
**Figure 7 Capacitance vs Vds**



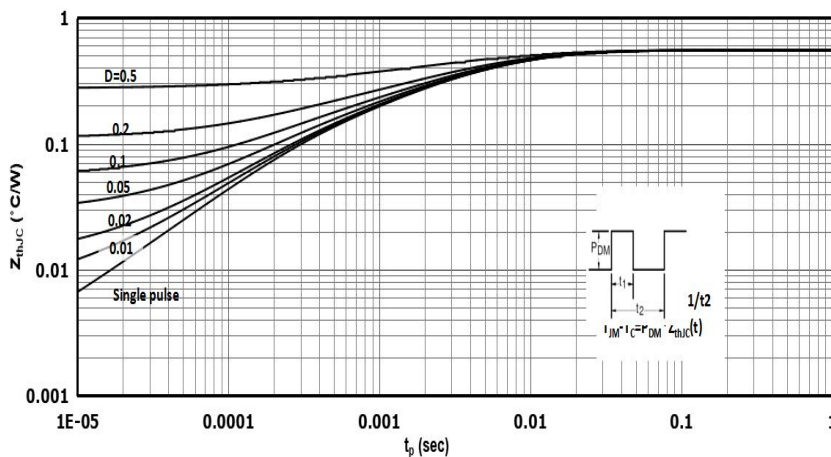
**Figure 8 Safe Operation Area**



**Figure 9. ID Current De-rating**

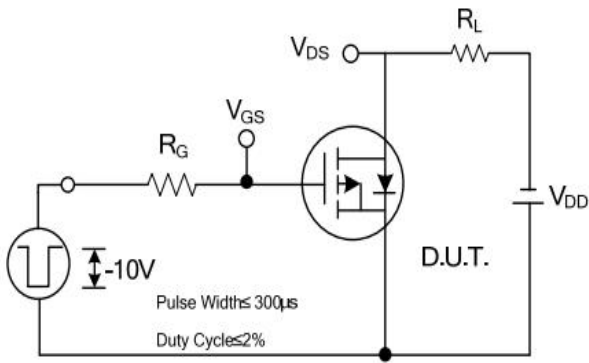


**Figure 10. Power De-rating**

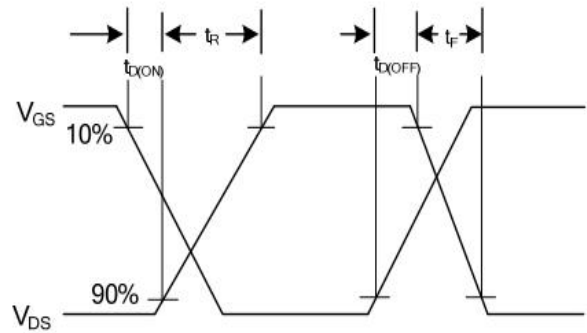


**Fig 11. Normalized Maximum Transient Thermal Impedance**

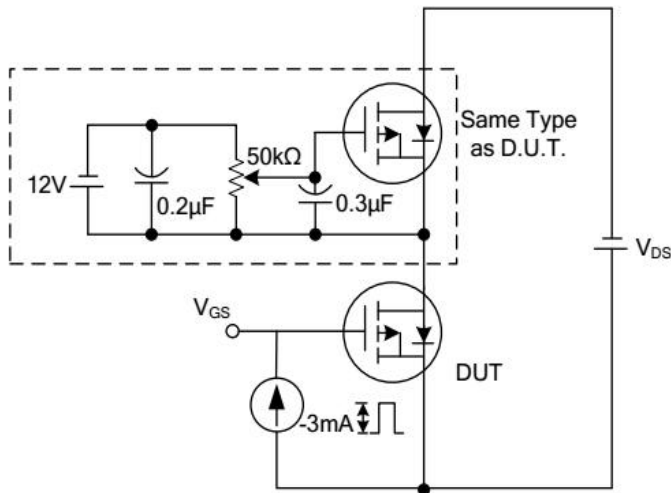
**6 Typical Test Circuit and Waveform**



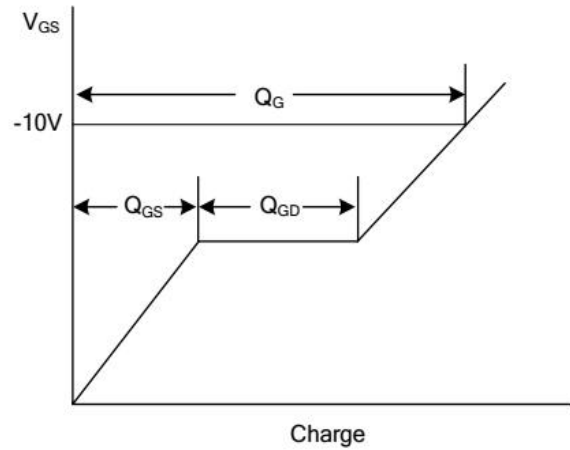
**Switching Test Circuit**



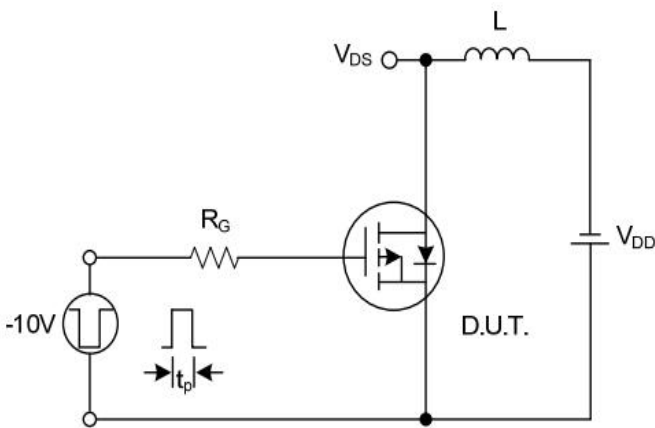
**Switching Waveforms**



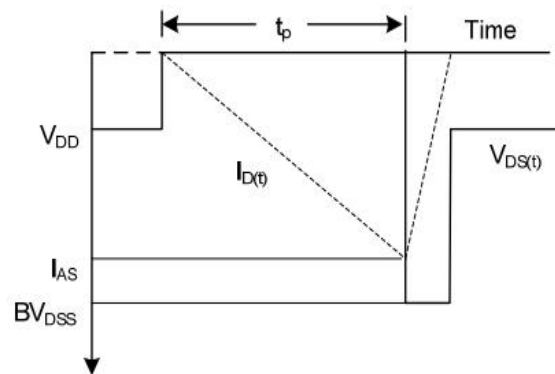
**Gate Charge Test Circuit**



**Gate Charge Waveform**

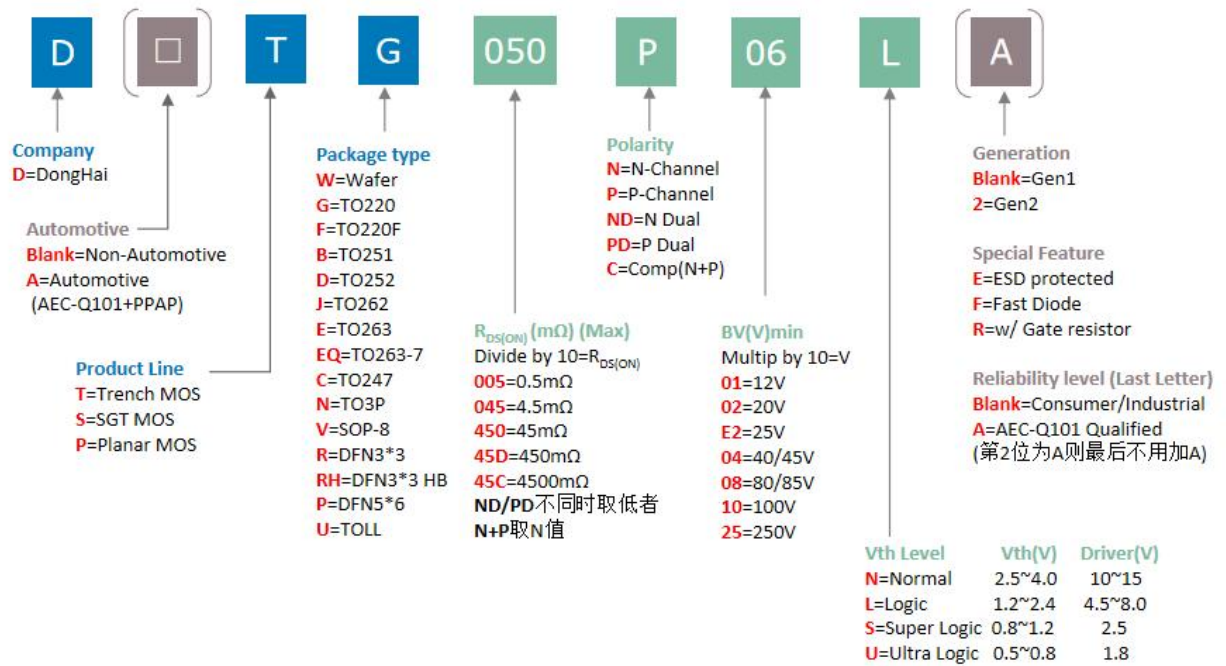


**Unclamped Inductive Switching Test Circuit**



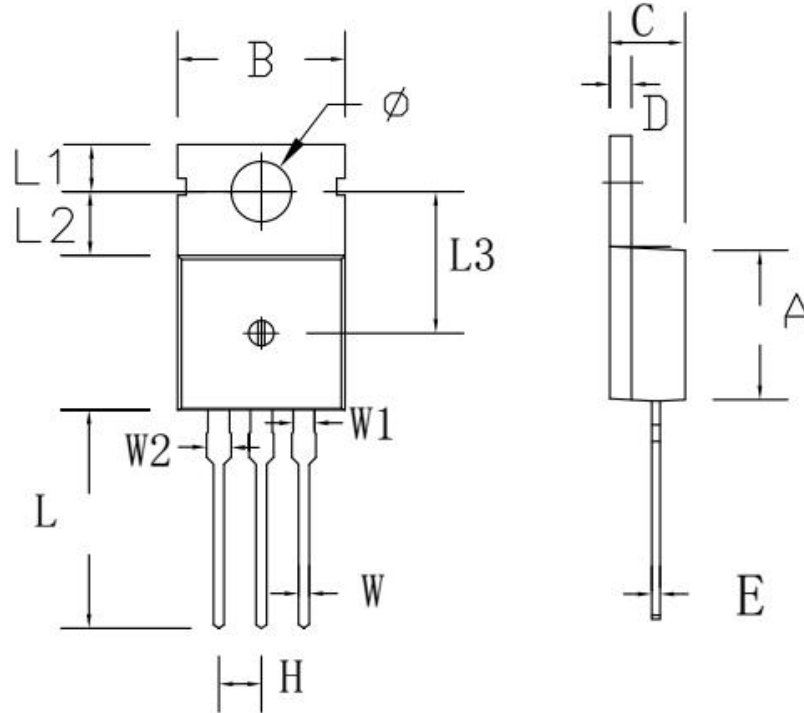
**Unclamped Inductive Switching Waveforms**

## 7 Product Names Rules



## 8 Product Specifications and Packaging Models

Product Model	Package Type	Mark Name	RoHS	Package	Quantity
DTG050P06LA	TO-220	DTG050P06LA	Pb-free	Tube	1000/box

**9 Dimensions**
**TO-220C PACKAGE OUTLINE DIMENSIONS**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
H	2.54 TYP		0.100 TYP	
W	0.60	0.95	0.024	0.037
W1	1.05	1.45	0.041	0.057
W2	1.20	1.60	0.047	0.063
L	12.60	13.40	0.496	0.528
L1	2.45	2.95	0.096	0.116
L2	3.45	3.95	0.136	0.156
L3	8.15	8.65	0.321	0.341
Φ	3.50	3.90	0.138	0.154

## 10 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

## 11 Appendix

Revision history:

Date	REV.	Description	Page
2022.10.25	1.0	Original	9